87C552

Single-chip 8-bit microcontroller with 10-bit A/D, capture/compare timer, high-speed outputs, PWM

DESCRIPTION

The 87C552 Single-Chip 8-Bit Microcontroller is manufactured in an advanced CMOS process and is a derivative of the 80C51 microcontroller family. The 87C552 has the same instruction set as the 80C51. Three versions of the derivative exist:

- 83C552—8k bytes mask programmable ROM
- 80C552—ROMless version of the 83C552
- 87C552—8k bytes EPROM

The 87C552 contains a 8k × 8 a volatile 256 × 8 read/write data memory, five 8-bit I/O ports, one 8-bit input port, two 16-bit timer/event counters (identical to the timers of the 80C51), an additional 16-bit timer coupled to capture and compare latches, a 15-source, two-priority-level, nested interrupt structure, an 8-input ADC, a dual DAC pulse width modulated interface, two serial interfaces (UART and I²C-bus), a "watchdog" timer and on-chip oscillator and timing circuits. For systems that require extra capability, the 87C552 can be expanded using standard TTL compatible memories and logic.

In addition, the 87C552 has two software selectable modes of power reduction-idle mode and power-down mode. The idle mode freezes the CPU while allowing the RAM, timers, serial ports, and interrupt system to continue functioning. The power-down mode saves the RAM contents but freezes the oscillator, causing all other chip functions to be inoperative.

The device also functions as an arithmetic processor having facilities for both binary and BCD arithmetic plus bit-handling capabilities. The instruction set consists of over 100 instructions: 49 one-byte, 45 two-byte, and 17 three-byte. With a 16MHz (24MHz) crystal, 58% of the instructions are executed in 0.75µs (0.5µs) and 40% in 1.5µs (1µs). Multiply and divide instructions require 3µs (2µs).



FEATURES

- 80C51 central processing unit
- 8k × 8 EPROM expandable externally to 64k bytes
- An additional 16-bit timer/counter coupled to four capture registers and three compare reaisters
- Two standard 16-bit timer/counters
- 256 × 8 RAM, expandable externally to 64k bytes
- Capable of producing eight synchronized, timed outputs
- A 10-bit ADC with eight multiplexed analog inputs
- Two 8-bit resolution, pulse width modulation outputs
- Five 8-bit I/O ports plus one 8-bit input port shared with analog inputs
- I²C-bus serial I/O port with byte oriented master and slave functions
- Full-duplex UART compatible with the standard 80C51
- On-chip watchdog timer
- Three speed ranges:
- 16MHz
- Extended temperature ranges
- OTP package available

PIN CONFIGURATIONS

		1 O CERAMIC AND PLASTIC LEADED IP CARRIEN	61 60 R 44
Pin 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 21 22 23 24 25 26 27 29 30 31 22 33 34 33 34 33 34 34 34 35 36 36 37 36 37 37 37 37 37 37 37 37 37 37	Function P5.0/ADC0 VDD STADC PWM0 P4.0/CMSR0 P4.1/CMSR1 P4.2/CMSR2 P4.3/CMSR3 P4.4/CMSR4 P4.5/CMSR3 P4.4/CMSR4 P4.5/CMSR3 P4.6/CMT0 P4.7/CMT1 R5T P1.0/CT01 P1.1/CT11 P1.2/CT21 P1.3/CT31 P1.4/T2 P1.6/SCL P1.7/SDA P3.0/RXD P3.3/INT1 P3.4/T0 P3.5/T1 P3.6/WR P3.7/RD NC NC XTAL2	Pin 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52 53 55 56 57 58 60 61 62 63 64 65 66 67 68	Function XTAL1 Vss Vss NC P2.0/A08 P2.1/A09 P2.2/A10 P2.3/A11 P2.4/A12 P2.5/A13 P2.6/A14 P2.7/A15 PSEN ALE/PROG EA/Vpp P0.7/AD7 P0.6/AD6 P0.5/AD5 P0.4/AD4 P0.3/AD3 P0.2/AD2 P0.1/AD1 P0.3/AD3 P0.2/AD2 P0.1/AD1 P0.3/AD3 P0.2/AD2 P0.1/AD1 P0.3/AD3 P0.2/AD2 P0.1/AD1 P0.3/AD3 P0.2/AD2 P0.1/AD1 P0.5/ADC5 P5.5/ADC5 P5.5/ADC3 P5.2/ADC3 P5.2/ADC1
1 24	80	PQFP	

SU00208

PLASTIC QUAD FLAT PACK PIN FUNCTIONS



LOGIC SYMBOL



ORDERING INFORMATION

PART ORD	LIPS ER NUMBER IARKING		RICA PHILIPS ER NUMBER	DRAWING	TEMPERATURE °C	FREQ
ROMIess	ROM	ROMIess ROM		NUMBER	AND PACKAGE	MHz
PCB80C552-5-16WP	PCB83C552-5WP/xxx	S80C552-4A68	S83C552-4A68	SOT188-3	0 to +70, Plastic Leaded Chip Carrier	16
PCB80C552-5-16H	PCB83C552-5H/xxx	S80C552-4B	S83C552-4B	SOT318-2	0 to +70, Plastic Quad Flat Pack	16
PCF80C552-5-16WP	PCF83C552-5WP/xxx	S80C552-5A68	S83C552-5A68	SOT188-3	-40 to +85, Plastic Leaded Chip Carrier	16
PCF80C552-5-16H	PCF83C552-5H/xxx	S80C552-5B	S83C552-5B	SOT318-2	–40 to +85, Plastic Quad Flat Pack	16
PCA80C552-5-16WP	PCA83C552-5WP/xxx	S80C552-6A68	S83C552-6A68	SOT188-3	–40 to +125, Plastic Leaded Chip Carrier	16
PCA80C552-5-16H	PCA83C552-5H/xxx	S80C552-6B	S83C552-6B	SOT318-2	–40 to +125, Plastic Quad Flat Pack	16
PCB80C552-5-24WP	PCB83C552-5WP/xxx	S80C552-AA68	S83C552-AA68	SOT188-3	0 to +70, Plastic Leaded Chip Carrier	24
PCB80C552-5-24H	PCB83C552-5H/xxx	S80C552-AB	S83C552-AB	SOT318-2	0 to +70, Plastic Quad Flat Pack	24
PCF80C552-5-24WP	PCF83C552-5WP/xxx	S80C552-BA68	S83C552-BA68	SOT188-3	-40 to +85, Plastic Leaded Chip Carrier	24
PCF80C552-5-24H	PCF83C552-5H/xxx	S80C552-BB	S83C552-BB	SOT318-2	–40 to +85, Plastic Quad Flat Pack	24
PCB80C552-5-30WP	PCB83C552-5WP/xxx	S80C552-CA68	S83C552-CA68	SOT188-3	0 to +70, Plastic Leaded Chip Carrier	30
PCB80C552-5-30H	PCB83C552-5H/xxx	S80C552-CB	S83C552-CB	SOT318-2	0 to +70, Plastic Quad Flat Pack	30

NOTE:

1. xxx denotes the ROM code number.

	DRAWING	TEMPERATURE °C	FREQ
EPROM	NUMBER	AND PACKAGE	MHz
S87C552-4A68	SOT188-3	0 to +70, Plastic Leaded Chip Carrier	16
S87C552-4K68	1473A	0 to +70, Ceramic Leaded Chip Carrier w/Window	16
S87C552-4BA	SOT318-2	0 to +70, Plastic Quad Flat Pack	16
S87C552-5A68	SOT188-3	-40 to +85, Plastic Leaded Chip Carrier	16
S87C552-5K68	1473A	-40 to +85, Ceramic Leaded Chip Carrier w/Window	16
S87C552-5BA	SOT318-2	–40 to +85, Plastic Quad Flat Pack	16

BLOCK DIAGRAM



PIN DESCRIPTION

	PIN NO.			
MNEMONIC	PLCC	QFP	ТҮРЕ	NAME AND FUNCTION
V _{DD}	2	72	I	Digital Power Supply: +5V power supply pin during normal operation, idle and power-down mode.
STADC	3	74	I	Start ADC Operation: Input starting analog to digital conversion (ADC operation can also be started by software).
PWM0	4	75	0	Pulse Width Modulation: Output 0.
PWM1	5	76	0	Pulse Width Modulation: Output 1.
EW	6	77	I.	Enable Watchdog Timer: Enable for T3 watchdog timer and disable power-down mode.
P0.0-P0.7	57-50	58-51	I/O	Port 0: Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application it uses strong internal pull-ups when emitting 1s. Port 0 is also used to input the code byte during programming and to output the code byte during verification.
P1.0-P1.7	16-23	10-17	I/O	Port 1: 8-bit I/O port. Alternate functions include:
	16-21	10-15	I/O	(P1.0-P1.5): Quasi-bidirectional port pins.
	22-23	16-17	I/O	(P1.6, P1.7): Open drain port pins.
	16-19	10-13		CT0I-CT3I (P1.0-P1.3): Capture timer input signals for timer T2.
	20	14		T2 (P1.4): T2 event input.
	21	15		RT2 (P1.5): T2 timer reset signal. Rising edge triggered.
	22	16	1/0	SCL (P1.6): Serial port clock line I ² C-bus.
	23	17	I/O	SDA (P1.7): Serial port data line I ² C-bus.
				Port 1 is also used to input the lower order address byte during EPROM programming and verification. A0 is on P1.0, etc.
P2.0-P2.7	39-46	38-42, 45-47	I/O	Port 2: 8-bit quasi-bidirectional I/O port. Alternate function: High-order address byte for external memory (A08-A15). Port 2 is also used to input the upper order address during EPROM programming and verification. A8 is on P2.0, A9 on P2.1, through A12 on P2.4.
P3.0-P3.7	24-31	18-20, 23-27	I/O	Port 3: 8-bit quasi-bidirectional I/O port. Alternate functions include:
	24	18		RxD(P3.0): Serial input port.
	25	19		TxD (P3.1): Serial output port.
	26	20		INTO (P3.2): External interrupt.
	27	23		INT1 (P3.3): External interrupt.
	28	24		T0 (P3.4): Timer 0 external input.
	29	25		T1 (P3.5): Timer 1 external input.
	30	26		WR (P3.6): External data memory write strobe.
	31	27		RD (P3.7): External data memory read strobe.
P4.0-P4.7	7-14	80, 1-2 4-8	I/O	Port 4: 8-bit quasi-bidirectional I/O port. Alternate functions include:
	7-12	80, 1-2 4-6	0	CMSR0-CMSR5 (P4.0-P4.5): Timer T2 compare and set/reset outputs on a match with timer T2.
	13, 14	7, 8	0	CMT0, CMT1 (P4.6, P4.7): Timer T2 compare and toggle outputs on a match with timer T2.
P5.0-P5.7	68-62, 1	71-64,	I	Port 5: 8-bit input port. ADC0-ADC7 (P5.0-P5.7): Alternate function: Eight input channels to ADC.
RST	15	9	I/O	Reset: Input to reset the 87C552. It also provides a reset pulse as output when timer T3 overflows.
XTAL1	35	32	I	Crystal Input 1: Input to the inverting amplifier that forms the oscillator, and input to the internal clock generator. Receives the external clock signal when an external oscillator is used.
XTAL2	34	31	0	Crystal Input 2: Output of the inverting amplifier that forms the oscillator. Left open-circuit when an external clock is used.
V _{SS}	36, 37	34-36	Т	Digital ground.
PSEN	47	48	0	Program Store Enable: Active-low read strobe to external program memory.

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PIN DESCRIPTION (Continued)

	PIN	NO.		
MNEMONIC	PLCC	QFP	TYPE	NAME AND FUNCTION
ALE/PROG	48	49	0	Address Latch Enable: Latches the low byte of the address during accesses to external memory. It is activated every six oscillator periods. During an external data memory access, one ALE pulse is skipped. ALE can drive up to eight LS TTL inputs and handles CMOS inputs without an external pull-up. This pin is also the program pulse input (PROG) during EPROM programming.
EA/V _{PP}	49	50	I	External Access: When $\overline{\text{EA}}$ is held at TTL level high, the CPU executes out of the internal program ROM provided the program counter is less than 8192. When $\overline{\text{EA}}$ is held at TTL low level, the CPU executes out of external program memory. $\overline{\text{EA}}$ is not allowed to float. This pin also receives the 12.75V programming supply voltage (V _{PP}) during EPROM programming.
AV _{REF-}	58	59	I	Analog to Digital Conversion Reference Resistor: Low-end.
AV _{REF+}	59	60	I	Analog to Digital Conversion Reference Resistor: High-end.
AV _{SS}	60	61	I	Analog Ground
AV _{DD}	61	63	I	Analog Power Supply

NOTE:

1. To avoid "latch-up" effect at power-on, the voltage on any pin at any time must not be higher or lower than V_{DD} + 0.5V or V_{SS} – 0.5V, respectively.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator, as shown in the logic symbol.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

RESET

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on V_{DD} and RST must come up at the same time for a proper start-up.

IDLE MODE

In the idle mode, the CPU puts itself to sleep while some of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

POWER-DOWN MODE

In the power-down mode, the oscillator is stopped and the instruction to invoke power-down is the last instruction executed. Only the contents of the on-chip RAM are preserved. A hardware reset is the only way to terminate the power-down mode. The control bits for the reduced power modes are in the special function register PCON. Table 1 shows the state of the I/O ports during low current operating modes.

MODE	PROGRAM MEMORY	ALE	PSEN	PORT 0	PORT 1	PORT 2	PORT 3	PORT 4	PWM0/ PWM1
Idle	Internal	1	1	Data	Data	Data	Data	Data	High
Idle	External	1	1	Float	Data	Address	Data	Data	High
Power-down	Internal	0	0	Data	Data	Data	Data	Data	High
Power-down	External	0	0	Float	Data	Data	Data	Data	High

87C552

Serial Control Register (S1CON) – See Table 2

S1CON (D8H)

	. ,						
0.00	ENIOA	074	070	01		0.04	000
CR2	ENS1	STA	510	51	AA	CR1	CR0

Bits CR0, CR1 and CR2 determine the serial clock frequency that is generated in the master mode of operation.

Table 2. Serial Clock Rates

			BIT FRE	BIT FREQUENCY (kHz) AT f _{OSC}		
CR2	CR1	CR0	6MHz	12MHz	16MHz	f _{OSC} DIVIDED BY
0	0	0	23	47	62.5	256
0	0	1	27	54	71	224
0	1	0	31.25	62.5	83.3	192
0	1	1	37	75	100	160
1	0	0	6.25	12.5	17	960
1	0	1	50	100	133 ¹	120
1	1	0	100	200	267 ¹	60
1	1	1	0.25 < 62.5	0.5 < 62.5	0.67 < 56	96 $ imes$ (256 – (reload value Timer 1))
			0 to 225	0 to 224	0 to 223	Timer 1 in Mode 2.

NOTE:

1. These frequencies exceed the upper limit of 100kHz of the I²C-bus specification and cannot be used in an I²C-bus application.

ABSOLUTE MAXIMUM RATINGS1, 2, 3

PARAMETER	RATING	UNIT
Storage temperature range	-65 to +150	°C
Voltage on \overline{EA}/V_{PP} to V_{SS}	-0.5 to +13	V
Voltage on any other pin to V_{SS}	-0.5 to +6.5	V
Input, output DC current on any single I/O pin	5.0	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.0	W

NOTES:

1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.

2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.

 Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

DEVICE SPECIFICATIONS

	SUPPLY VOLTAGE (V)		FREQUEN	ICY (MHz)	
ТҮРЕ	MIN	MAX	MIN	MAX	TEMPERATURE RANGE (°C)
P87C552-4	4.5	5.5	3.5	16	0 to +70
P87C552-5	4.5	5.5	3.5	16	-40 to +85

87C552

DC ELECTRICAL CHARACTERISTICS

		TEST	LIN		
SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
I _{DD}	Supply current operating: PCA8XC552-5-16	See notes 1 and 2 f _{OSC} = 16MHz		40	mA
l	Idle mode:	See notes 1 and 3		40	
I _{ID}	87C552	f _{OSC} = 16MHz		7	mA
I _{PD}	Power-down current:	See notes 1 and 4;			
	87C552	2V < V _{PD} < V _{DD} max		50	μA
Inputs	L				
V _{IL}	Input low voltage, except EA, P1.6, P1.7		-0.5	0.2V _{DD} -0.1	V
V _{IL1}	Input low voltage to EA		-0.5	0.2V _{DD} -0.3	V
V _{IL2}	Input low voltage to P1.6/SCL, P1.7/SDA ⁵		-0.5	0.3V _{DD}	V
VIH	Input high voltage, except XTAL1, RST		0.2V _{DD} +0.9	V _{DD} +0.5	V
V _{IH1}	Input high voltage, XTAL1, RST		0.7V _{DD}	V _{DD} +0.5	V
V _{IH2}	Input high voltage, P1.6/SCL, P1.7/SDA ⁵		0.7V _{DD}	6.0	V
IIL	Logical 0 input current, ports 1, 2, 3, 4, except P1.6, P1.7	V _{IN} = 0.45V		-50	μA
I _{TL}	Logical 1-to-0 transition current, ports 1, 2, 3, 4, except P1.6, P1.7	See note 6		-650	μA
±I _{IL1}	Input leakage current, port 0, EA, STADC, EW	0.45V < V _I < V _{DD}		10	μA
±I _{IL2}	Input leakage current, P1.6/SCL, P1.7/SDA	0V < V _I < 6V 0V < V _{DD} < 5.5V		10	μA
±I _{IL3}	Input leakage current, port 5	0.45V < V _I < V _{DD}		1	μA
Outputs					
V _{OL}	Output low voltage, ports 1, 2, 3, 4, except P1.6, P1.7	I _{OL} = 1.6mA ⁷		0.45	V
V _{OL1}	Output low voltage, port 0, ALE, <u>PSEN</u> , <u>PWM0</u> , <u>PWM1</u>	$I_{OL} = 3.2 \text{mA}^7$		0.45	V
V _{OL2}	Output low voltage, P1.6/SCL, P1.7/SDA	I _{OL} = 3.0mA ⁷		0.4	V
V _{OH}	Output high voltage, ports 1, 2, 3, 4, except P1.6/SCL, P1.7/SDA	–l _{OH} = 60μA –l _{OH} = 25μA –l _{OH} = 10μA	2.4 0.75V _{DD} 0.9V _{DD}		V V V
V _{OH1}	Output high voltage (port 0 in external bus mode, ALE, PSEN, PWM0, PWM1) ⁸	–l _{OH} = 400μA –l _{OH} = 150μA –l _{OH} = 40μA	2.4 0.75V _{DD} 0.9V _{DD}		V V V
V _{OH2}	Output high voltage (RST)	–l _{OH} = 400μA –l _{OH} = 120μA	2.4 0.8V _{DD}		V V
R _{RST}	Internal reset pull-down resistor		50	150	kΩ
C _{IO}	Pin capacitance	Test freq = 1MHz, T _{amb} = 25°C		10	pF
Analog In	puts				-
AV _{DD}	Analog supply voltage: 87C552 ⁹	AV _{DD} = V _{DD} ±0.2V	4.5	5.5	v
Al _{DD}	Analog supply current: operating:	Port 5 = 0 to AV_{DD}		1.2	mA
Al _{ID}	Idle mode: 87C552			50	μA
Al _{PD}	Power-down mode: 87C552	2V < AV _{PD} < AV _{DD} max		50	μA

DC ELECTRICAL CHARACTERISTICS (Continued)

		TEST	LIMITS		UNIT
SYMBOL	PARAMETER	CONDITIONS	MIN MAX		
Analog In	puts (Continued)			_	
AV _{IN}	Analog input voltage		AV _{SS} -0.2	AV _{DD} +0.2	V
AV _{REF}	Reference voltage: AV _{REF-} AV _{REF+}		AV _{SS} -0.2	AV _{DD} +0.2	V V
R _{REF}	Resistance between AV _{REF+} and AV _{REF-}		10	50	kΩ
C _{IA}	Analog input capacitance			15	pF
t _{ADS}	Sampling time			8t _{CY}	μs
t _{ADC}	Conversion time (including sampling time)			50t _{CY}	μs
DLe	Differential non-linearity ^{10, 11, 12}			±1	LSB
IL _e	Integral non-linearity ^{10, 13}			±2	LSB
OS _e	Offset error ^{10, 14}			±2	LSB
G _e	Gain error ^{10, 15}			±0.4	%
A _e	Absolute voltage error ^{10, 16}			±3	LSB
M _{CTC}	Channel to channel matching			±1	LSB
Ct	Crosstalk between inputs of port 5 ¹⁷	0–100kHz		-60	dB

NOTES FOR DC ELECTRICAL CHARACTERISTICS:

1. See Figures 10 through 15 for I_{DD} test conditions.

2. The operating supply current is measured with all output pins disconnected; XTAL1 driven with $t_r = t_f = 10ns$; $V_{II} = V_{SS} + 0.5V$; $V_{IH} = V_{DD} - 0.5V$; XTAL2 not connected; $\overline{EA} = RST = Port 0 = \overline{EW} = V_{DD}$; STADC = V_{SS} .

The idle mode supply current is measured with all output pins disconnected; XTAL1 driven with $t_r = t_f = 10ns$; $V_{IL} = V_{SS} + 0.5V$; 3. $V_{IH} = V_{DD} - 0.5V$; XTAL2 not connected; Port 0 = $\overline{EW} = V_{DD}$; $\overline{EA} = RST = STADC = V_{SS}$.

The power-down current is measured with all output pins disconnected; XTAL2 not connected; Port 0 = EW = V_DD; \overline{EA} = RST = STADC = XTAL1 = V_{SS}.

The input threshold voltage of P1.6 and P1.7 (SIO1) meets the l^2C specification, so an input voltage below 1.5V will be recognized as a logic 0 while an input voltage above 3.0V will be recognized as a logic 1.

Pins of ports 1 (except P1.6, P1.7), 2, 3, and 4 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when $V_{\mbox{IN}}$ is approximately 2V.

7. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the Vols of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. In exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and PSEN to momentarily fall below the 0.9 V_{DD} specification when the

8 address bits are stabilizing.

9 The following condition must not be exceeded: $V_{DD} - 0.2V < AV_{DD} < V_{DD} + 0.2V$.

10. Conditions: $AV_{REF-} = 0V$; $AV_{DD} = 5.0V$. Measurement by continuous conversion of $AV_{IN} = -20mV$ to 5.12V in steps of 0.5mV, derivating parameters from collected conversion results of ADC. AV_{REF+} (87C552) = 4.977V. ADC is monotonic with no missing codes.

11. The differential non-linearity (DL_e) is the difference between the actual step width and the ideal step width. (See Figure 1.)

- 12. The ADC is monotonic; there are no missing codes.
- 13. The integral non-linearity (ILe) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset error. (See Figure 1.)
- 14. The offset error (OSe) is the absolute difference between the straight line which fits the actual transfer curve (after removing gain error), and a straight line which fits the ideal transfer curve. (See Figure 1.)
- 15. The gain error (Ge) is the relative difference in percent between the straight line fitting the actual transfer curve (after removing offset error), and the straight line which fits the ideal transfer curve. Gain error is constant at every point on the transfer curve. (See Figure 1.)
- The absolute voltage error (Ae) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve.
- 17. This should be considered when both analog and digital signals are simultaneously input to port 5.



Figure 1. ADC Conversion Characteristic

AC ELECTRICAL CHARACTERISTICS^{1, 2}

			12MHz CLOCK		16MHz CLOCK		VARIABLE CLOCK		
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
1/t _{CLCL}	2	Oscillator frequency					3.5	16	MHz
t _{LHLL}	2	ALE pulse width	127		85		2t _{CLCL} -40		ns
t _{AVLL}	2	Address valid to ALE low	28		8		t _{CLCL} –55		ns
t _{LLAX}	2	Address hold after ALE low	48		28		t _{CLCL} -35		ns
t _{LLIV}	2	ALE low to valid instruction in		234		150		4t _{CLCL} -100	ns
t _{LLPL}	2	ALE low to PSEN low	43		23		t _{CLCL} -40		ns
t _{PLPH}	2	PSEN pulse width	205		143		3t _{CLCL} -45		ns
t _{PLIV}	2	PSEN low to valid instruction in		145		83		3t _{CLCL} -105	ns
t _{PXIX}	2	Input instruction hold after PSEN	0		0		0		ns
t _{PXIZ}	2	Input instruction float after PSEN		59		38		t _{CLCL} -25	ns
t _{AVIV}	2	Address to valid instruction in		312		208		5t _{CLCL} -105	ns
t _{PLAZ}	2	PSEN low to address float		10		10		10	ns
Data Memo	ry					· · · · ·			
t _{AVLL}	3, 4	Address valid to ALE low	43		23		t _{CLCL} -40		ns
t _{RLRH}	3	RD pulse width	400		275		6t _{CLCL} -100		ns
twlwh	3	WR pulse width	400		275		6t _{CLCL} -100		ns
t _{RLDV}	3	RD low to valid data in		252		148		5t _{CLCL} -165	ns
t _{RHDX}	3	Data hold after RD	0		0		0		ns
t _{RHDZ}	3	Data float after RD		97		55		2t _{CLCL} -70	ns
t _{LLDV}	3	ALE low to valid data in		517		350		8t _{CLCL} -150	ns
t _{AVDV}	3	Address to valid data in		585		398		9t _{CLCL} -165	ns
t _{LLWL}	3, 4	ALE low to RD or WR low	200	300	138	238	3t _{CLCL} -50	3t _{CLCL} +50	ns
t _{AVWL}	3, 4	Address valid to WR low or RD low	203		120		4t _{CLCL} -130		ns
t _{QVWX}	4	Data valid to WR transition	23		3		t _{CLCL} -60		ns
t _{DW}	4	Data before WR	433		288		7t _{CLCL} -150		ns
t _{WHQX}	4	Data hold after WR	33		13		t _{CLCL} -50		ns
t _{RLAZ}	4	RD low to address float		0		0		0	ns
t _{WHLH}	3, 4	RD or WR high to ALE high	43	123	23	103	t _{CLCL} -40	t _{CLCL} +40	ns
External Cl	ock								
t _{CHCX}	5	High time ³	20		20		20		ns
t _{CLCX}	5	Low time ³	20		20		20		ns
t _{CLCH}	5	Rise time ³		20		20		20	ns
t _{CHCL}	5	Fall time ³		20		20		20	ns
	ng – Shift R	egister Mode ⁴ (Test Conditions: T _{amb} = 0	0°C to +7	0°C; V _{SS}	- = 0V; Loa	Id Capacia	atnce = 80pF)		
t _{XLXL}	6	Serial port clock cycle time	1.0		0.75		12t _{CLCL}		μs
t _{QVXH}	6	Output data setup to clock rising edge	700		492		10t _{CLCL} -133		ns
t _{XHQX}	6	Output data hold after clock rising edge	50		8		2t _{CLCL} -117		ns
t _{XHDX}	6	Input data hold after clock rising edge	0	1	0		0		ns
t _{XHDV}	6	Clock rising edge to input data valid		700		492		10t _{CLCL} -133	ns

NOTES:

Parameters are valid over operating temperature range unless otherwise specified.
Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
t_{CLCL} = 1/f_{OSC} = one oscillator clock period. t_{CLCL} = 83.3ns at f_{OSC} = 12MHz. t_{CLCL} = 62.5ns at f_{OSC} = 16MHz.
These values are characterized but not 100% production tested.

AC ELECTRICAL CHARACTERISTICS (Continued)

SYMBOL	PARAMETER	INPUT	OUTPUT		
I ² C Interfac	re (Refer to Figure 9) ⁵				
t _{HD;STA}	START condition hold time	\geq 14 t _{CLCL}	> 4.0µs ¹		
t _{LOW}	SCL low time	≥ 16 t _{CLCL}	> 4.7µs ¹		
t _{HIGH}	SCL high time	\geq 14 t _{CLCL}	> 4.0µs ¹		
t _{RC}	SCL rise time	≤ 1μs	- ²		
t _{FC}	SCL fall time	≤ 0.3µs	< 0.3μs ³		
t _{SU;DAT1}	Data set-up time	≥ 250ns	> 20 t _{CLCL} – t _{RD}		
t _{SU;DAT2}	SDA set-up time (before rep. START cond.)	≥ 250ns	> 1µs ¹		
t _{SU;DAT3}	SDA set-up time (before STOP cond.)	≥ 250ns	> 8 t _{CLCL}		
t _{HD;DAT}	Data hold time	≥ 0ns	> 8 t _{CLCL} – t _{FC}		
t _{SU;STA}	Repeated START set-up time	≥ 14 t _{CLCL}	> 4.7µs ¹		
t _{SU;STO}	STOP condition set-up time	≥ 14 t _{CLCL}	> 4.0µs ¹		
t _{BUF}	Bus free time	≥ 14 t _{CLCL}	> 4.7µs ¹		
t _{RD}	SDA rise time	≤ 1μs	_ ²		
t _{FD}	SDA fall time	≤ 0.3μs	< 0.3µs ³		

NOTES:

 At 100 kbit/s. At other bit rates this value is inversely proportional to the bit-rate of 100 kbit/s.
Determined by the external bus-line capacitance and the external bus-line pull-resistor, this must be < 1μs.
Spikes on the SDA and SCL lines with a duration of less than 3 t_{CLCL} will be filtered out. Maximum capacitance on bus-lines SDA and SCL = 400pF.

 $t_{CLCL} = 1/f_{OSC}$ = one oscillator clock period at pin XTAL1. For 62ns (42s) < t_{CLCL} < 285ns (16MHz (24Hz) > f_{OSC} > 3.5MHz) the SI01 interface meets the I²C-bus specification for bit-rates up to 100 kbit/s. These values are guaranteed but not 100% production tested. 4.

5.

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Single-chip 8-bit microcontroller

EXPLANATION OF THE AC SYMBOLS Each timing symbol has five characters. The Q – Output data



- C Clock
- D Input data
- H Logic level high
- I Instruction (program memory contents)
- L Logic level low, or ALE
- P PSEN



Z – Float

t – Time

R - RD signal

Examples: t_{AVLL} = Time for address valid to

ALE low.







Figure 2. External Program Memory Read Cycle



Figure 3. External Data Memory Read Cycle

87C552



Figure 4. External Data Memory Write Cycle



Figure 5. External Clock Drive XTAL1



Figure 6. Shift Register Mode Timing









Figure 8. AC Testing Input, Float Waveform



Figure 9. Timing SIO1 (I²C) Interface

87C552



Figure 10. 16MHz Version Supply Current (IDD) as a Function of Frequency at XTAL1 (fOSC)



Figure 11. I_{DD} Test Condition, Active Mode All other pins are disconnected¹

- 1. Active Mode:
 - a. The following pins must be forced to V_{DD}: \overline{EA} , RST, Port 0, and \overline{EW} . b. The following pins must be forced to V_{SS}: STADC, AV_{ss}, and AV_{ref}.

 - c. Ports 1.6 and 1.7 should be connected to V_{DD} through resistors of sufficiently high value such that the sink current into these pins cannot exceed the $I_{\mbox{\scriptsize OL1}}$ spec of these pins.
 - d. The following pins must be disconnected: XTAL2 and all pins not specified above.

Single-chip 8-bit microcontroller



Figure 12. I_{DD} Test Condition, Idle Mode All other pins are disconnected²

2. Idle Mode:

- a. The following pins must be forced to $V_{\mbox{DD}}{:}\,$ Port 0 and $\overline{\mbox{EW}}{.}$
- b. The following pins must be forced to V_{SS}: RST, STADC, AV_{ss},, AV_{ref-}, and \overline{EA} .
- c. Ports 1.6 and 1.7 should be connected to V_{DD} through resistors of sufficiently high value such that the sink current into these pins cannot exceed the I_{OL1} spec of these pins. These pins must not have logic 0 written to them prior to this measurement.
- d. The following pins must be disconnected: XTAL2 and all pins not specified above.



Figure 13. Clock Signal Waveform for I_{DD} Tests in Active and Idle Modes $t_{CLCH} = t_{CHCL} = 5ns$



Figure 14. I_{DD} Test Condition, Power Down Mode All other pins are disconnected. V_{DD} = 2V to $5.5V^3$

- 3. Power Down Mode:
 - a. The following pins must be forced to V_{DD} : Port 0 and \overline{EW} .
 - b. The following pins must be forced to V_SS: RST, STADC, XTAL1, AV_ss,, AV_{ref-}, and $\overline{\text{EA}}.$
 - c. Ports 1.6 and 1.7 should be connected to V_{DD} through resistors of sufficiently high value such that the sink current into these pins cannot exceed the I_{OL1} spec of these pins. These pins must not have logic 0 written to them prior to this measurement.
 - d. The following pins must be disconnected: XTAL2 and all pins not specified above.

EPROM CHARACTERISTICS

The 87C552 is programmed by using a modified Quick-Pulse Programming[™] algorithm. It differs from older methods in the value used for V_{PP} (programming supply voltage) and in the width and number of the ALE/PROG pulses.

The 87C552 contains two signature bytes that can be read and used by an EPROM programming system to identify the device. The signature bytes identify the device as an 87C552 manufactured by Philips.

Table 3 shows the logic levels for reading the signature byte, and for programming the program memory, the encryption table, and the lock bits. The circuit configuration and waveforms for quick-pulse programming are shown in Figures 15 and 16. Figure 17 shows the circuit configuration for normal program memory verification.

Quick-Pulse Programming

The setup for microcontroller quick-pulse programming is shown in Figure 15. Note that the 87C552 is running with a 4 to 6MHz oscillator. The reason the oscillator needs to be running is that the device is executing internal address and program data transfers.

The address of the EPROM location to be programmed is applied to ports 1 and 2, as shown in Figure 15. The code byte to be programmed into that location is applied to port 0. RST, <u>PSEN</u>, and pins of ports 2 and 3 specified in Table 3 are held at the "Program Code Data" levels indicated in Table 3. The ALE/PROG is pulsed low 25 times as shown in Figure 16.

To program the encryption table, repeat the 25-pulse programming sequence for

addresses 0 through 1FH, using the "Pgm Encryption Table" levels. Do not forget that after the encryption table is programmed, verification cycles will produce only encrypted data.

To program the lock bits, repeat the 25-pulse programming sequence using the "Pgm Lock Bit" levels. After one lock bit is programmed, further programming of the code memory and encryption table is disabled. However, the other lock bit can still be programmed.

Note that the \overline{EA}/V_{PP} pin must not be allowed to go above the maximum specified V_{PP} level for any amount of time. Even a narrow glitch above that voltage can cause permanent damage to the device. The V_{PP} source should be well regulated and free of glitches and overshoot.

Program Verification

If lock bit 2 has not been programmed, the on-chip program memory can be read out for program verification. The address of the program memory locations to be red is applied to ports 1 and 2 as shown in Figure 17. The other pins are held at the "Verify Code Data" levels indicated in Table 3. The contents of the address location will be emitted on port 0. External pull-ups are required on port 0 for this operation.

If the encryption table has been programmed, the data presented at port 0 will be the exclusive NOR of the program byte with one of the encryption bytes. The user will have to know the encryption table contents in order to correctly decode the verification data. The encryption table itself cannot be read out.

Reading the Signature Bytes

The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 need to be pulled to a logic low. The values are:

- (030H) = 15H indicates manufactured by Philips Components
- (031H) = 94H indicates 87C552

Program/Verify Algorithms

Any algorithm in agreement with the conditions listed in Table 3, and which satisfies the timing specifications, is suitable.

Erasure Characteristics

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelengths shorter than approximately 4,000 angstroms. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to the light sources over an extended time (about 1 week in sunlight, or 3 years in room level fluorescent lighting) could cause inadvertent erasure. For this and secondary effects, it is recommended that an opaque label be placed over the window. For elevated temperature or environments where solvents are being used, apply Kapton tape Fluorglas part number 2345-5, or equivalent.

The recommended erasure procedure is exposure to ultraviolet light (at 2537 angstroms) to an integrated dose of at least 15W-sec/cm². Exposing the EPROM to an ultraviolet lamp of 12,000 μ W/cm² rating for 20 to 39 minutes, at a distance of about 1 inch, should be sufficient. Erasure leaves the array in an all 1s state.

MODE	RST	PSEN	ALE/PROG	EA/V _{PP}	P2.7	P2.6	P3.7	P3.6
Read signature	1	0	1	1	0	0	0	0
Program code data	1	0	0*	V _{PP}	1	0	1	1
Verify code data	1	0	1	1	0	0	1	1
Pgm encryption table	1	0	0*	V _{PP}	1	0	1	0
Pgm lock bit 1	1	0	0*	V _{PP}	1	1	1	1
Pgm lock bit 2	1	0	0*	V _{PP}	1	1	0	0

Table 3. EPROM Programming Modes

NOTES:

1. 0 =Valid low for that pin; 1 =valid high for that pin.

2. $V_{PP} = 12.75V \pm 0.25V$.

3. V_{DD}^{i} = 5V ±10% during programming and verification.

ALE/PROG receives 25 programming pulses while V_{PP} is held at 12.75V. Each programming pulse is low for 100μs (±10μs) and high for a minimum of 10μs.

[™]Trademark phrase of Intel Corporation.



Figure 15. Programming Configuration



Figure 16. PROG Waveform



Figure 17. Program Verification

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

 T_{amb} = 21°C to +27°C, V_{DD} = 5V±10%, V_{SS} = 0V

SYMBOL	PARAMETER	MIN	MAX	UNIT	
V _{PP}	Programming supply voltage	12.5	13.0	V	
I _{PP}	Programming supply current		50	mA	
1/t _{CLCL}	Oscillator frequency	4	6	MHz	
t _{AVGL}	Address setup to PROG low	48t _{CLCL}			
t _{GHAX}	Address hold after PROG	48t _{CLCL}			
t _{DVGL}	Data setup to PROG low	48t _{CLCL}			
t _{GHDX}	Data hold after PROG	48t _{CLCL}			
t _{EHSH}	P2.7 (ENABLE) high to V _{PP}	48t _{CLCL}			
t _{SHGL}	V _{PP} setup to PROG low	10		μs	
t _{GHSL}	V _{PP} hold after PROG	10		μs	
t _{GLGH}	PROG width	90	110	μs	
t _{AVQV}	Address to data valid		48t _{CLCL}		
t _{ELQZ}	ENABLE low to data valid		48t _{CLCL}		
t _{EHQZ}	Data float after ENABLE	0	48t _{CLCL}		
t _{GHGL}	PROG high to PROG low	10		μs	



FOR PROGRAMMING VERIFICATION SEE FIGURE 17. FOR VERIFICATION CONDITIONS SEE TABLE 3.

Figure 18. EPROM Programming and Verification



Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specifications defined by Philips. This specification can be ordered using the code 9398 393 40011.